$T_{jmax} = 175$ °C Continuous Operation

- Low V_{CESAT} and Switching Losses
- Automotive Grade FS4 750 V Narrow Mesa IGBT
- Fast Recovery Diode Chip Technologies
- 4.2 kV Isolated DBC Substrate
- Easy to Integrate 6 pack Topology
- This Device is Pb Free and is RoHS Compliant

Typical Applications

• Hybrid and Electric Vehicle Traction Inverter Narrow Mesa IGBT

Pin Description

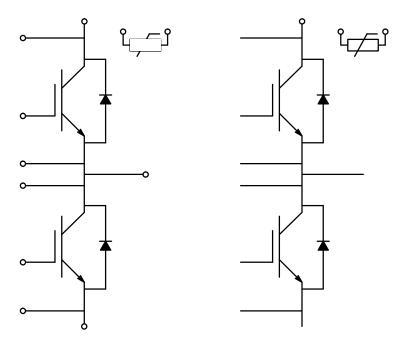


Figure 1. Pin Description

MODULE CHARACTERISTICS ($T_{vj} = 25^{\circ}_{C}$, Unless Otherwise Specified)

Symbol	Parameter	Rating	Unit
T_{vj}	Operating Junction Temperature	-40 to 175	°C
T _{STG}	Storage Temperature	-40 to 125	°C
V _{ISO}	Isolation Voltage (DC, 0 Hz, 1 s)	4200	V
L _{sCE}	Stray Inductance	10	nΗ
RCC'+EE'	Module Lead Resistance, Terminals – Chip	0.75	mΩ
G	Module Weight	700	g
CTI	Comparative Tracking Index	>200	-
d _{creep}	Creepage: Terminal to Heatsink Terminal to Terminal	9.0 9.0	mm
d _{clear}	Clearance: Terminal to Heatsink Terminal to Terminal	4.5 4.5	mm

Symbol	Parameters	Conditions	Min	Тур	Max	Unit
Δρ	Pressure Drop in Cooling Circuit	10 L/min, 65°C, 50/50 EGW	ı	95	-	mbar
P (Note 1)	Maximum Pressure in Cooling Loop (relative)	T _{Baseplate} < 40°C T _{Baseplate} > 40°C	1 1	-	2.5	

$\textbf{CHARACTERISTICS OF INVERSE DIODE} \ (T_{vj} = 25^{\circ}C, \ Unless \ Otherwise \ Specified)$

Symbol	Parameters	Condition	s	Min	Тур	Max	Unit
V _F	Diode Forward Voltage (Terminal)	I _F = 500 A	T _{vj} = 25°C	-	1.60	1.85	V
	Diode Forward Voltage (Chip)	I _F = 500 A	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	- - -	1.53 1.45 1.40	1.78 - -	
		I _F = 680 A	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	- - -	1.65 1.61 1.57	- - -	
E _{rr}	Reverse Recovery Energy	$I_F = 500 \text{ A}, V_R = 400 \text{ V}, V_{GE} = +15/-8 \text{ V}, R_{g.on} = 4.7 \Omega$	di/dt = 3.5 A/nS, $T_{vj} = 25^{\circ}\text{C}$ di/dt = 3.0 A/nS, $T_{vj} = 150^{\circ}\text{C}$	-	3 8	-	mJ
			di/dt = 2.8 A/nS, T _{vj} = 175°C	_	10	-	
Q_{RR}	Recovered Charge	$I_F = 500 \text{ A}, V_R = 400 \text{ V}, V_{GE} = -8 \text{ V},$	$di/dt = 3.5 \text{ A/nS},$ $T_{vj} = 25^{\circ}\text{C}$	-	11	-	μС
		$R_{g.on} = 4.7 \Omega$	di/dt = 3.0 A/nS, $T_{vj} = 150^{\circ}\text{C}$	-	32	-	
			$di/dt = 2.8 \text{ A/nS},$ $T_{vj} = 175^{\circ}\text{C}$	-	38	-	
I _{rr}	Peak Reverse Recovery Current	$I_F = 500 \text{ A}, V_R = 400 \text{ V},$ $V_{GE} = -8 \text{ V},$	$di/dt = 3.5 \text{ A/nS},$ $T_{vj} = 25^{\circ}\text{C}$	-	141	-	Α
		$R_{g.on} = 4.7 \Omega$	di/dt = 3.0 A/nS, $T_{vj} = 150^{\circ}\text{C}$	-	247	-	
			$di/dt = 2.8 \text{ A/nS},$ $T_{vj} = 175^{\circ}\text{C}$	-	265	_	

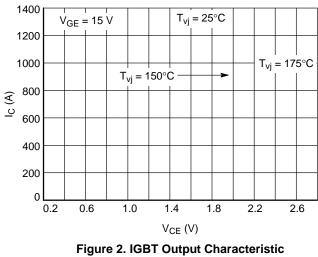
NTC SENSOR CHARACTERISTICS ($T_{vj} = 25^{\circ}C$, Unless Otherwise Specified)

Symbol	Parameters	Conditions	Min	Тур	Max	Unit
R ₂₅ (Note 3)	Rated Resistance	$T_C = 25^{\circ}C$	_	5147	_	Ω
ΔR/R	Deviation of R ₁₀₅	$T_C = 105^{\circ}C, R_{105} = 472 \Omega$	5	_	5	%
P ₂₅	Power Dissipation	T _C = 25°C	_	_	32	mW
B _{25/55}	B-Value	$R = R_{25} \exp [B_{25/55} (1/T - 1/298)]$	_	3340	_	K
B _{25/85}	B-Value	$R = R_{25} \exp [B_{25/85} (1/T - 1/298)]$	-	3360	-	K
B _{25/105}	B-Value	$R = R_{25} \exp \left[B_{25/105} \left(1/T - 1/298 \right) \right]$	_	3364	_	K

^{3.} Measured value at terminals.

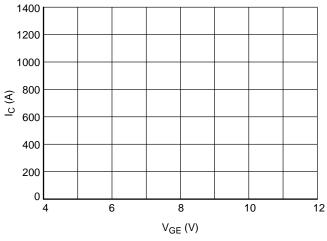
THERMAL CHARACTERISTICS

Symbol	Parameter	Min	Тур	Max	Unit
IGBT R45 1 F	R _{th.} Junction to Fluid, 10Ti6.5 0 0 6.5 132.831555 Tc(1/298)])TiFT226.998.2915	09 T59 75	4 29181 7	CO Tw(25)	Ti1 1164



1400 $V_{GE} = 17 V$ T_{vj} = 150°C 1200 1000 800 Ic (A) 600 400 200 0 2 0 V_{CE} (V)





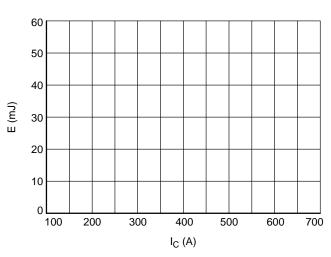
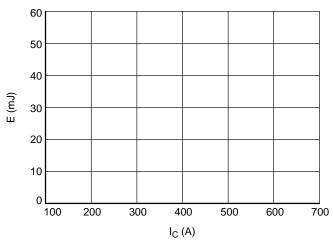


Figure 4. IGBT Transfer Characteristic

Figure 5. IGBT Turn-on Losses vs. I_C



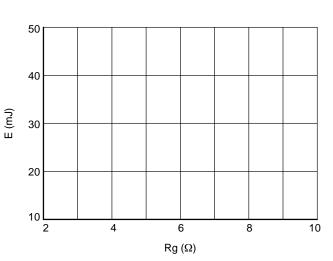
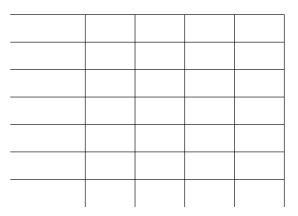
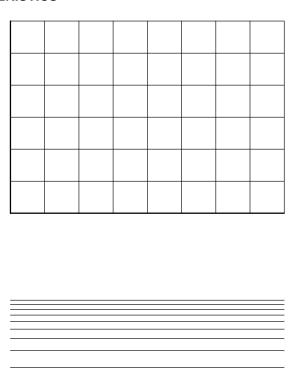
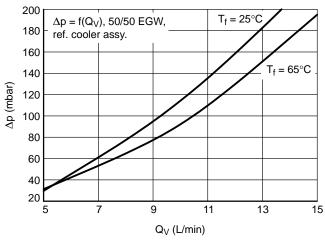


Figure 6. IGBT Turn-off Losses vs. I_C

Figure 7. Eon vs. Rg







100,000 10,000

Figure 20. Pressure Drop In Cooling Circuit

Figure 21. NTC Thermistor – Temperature Characteristic (Typical)

PACKAGE DIMENSIONS

SSDC33, 154.50x92.0 (SPB) CASE 183AB ISSUE A

PACKAGE DIMENSIONS

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